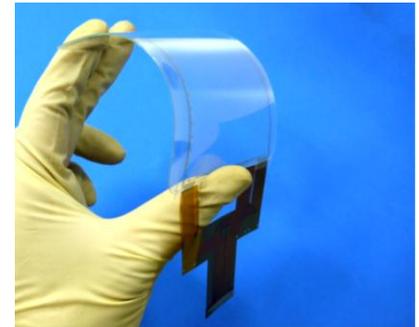


## Development of Printed Flex Circuits

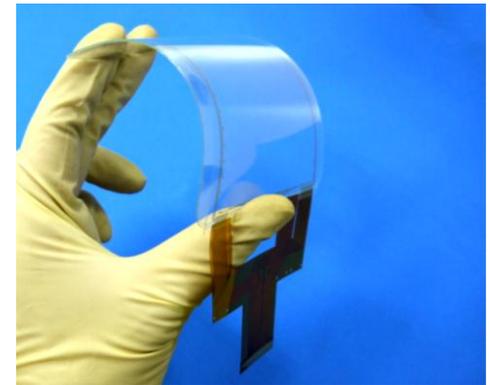


Hirofumi Matsumoto, Ph.D.  
Product development planning office  
Operating Officer and Division Manager  
Nippon Mektron, Ltd.

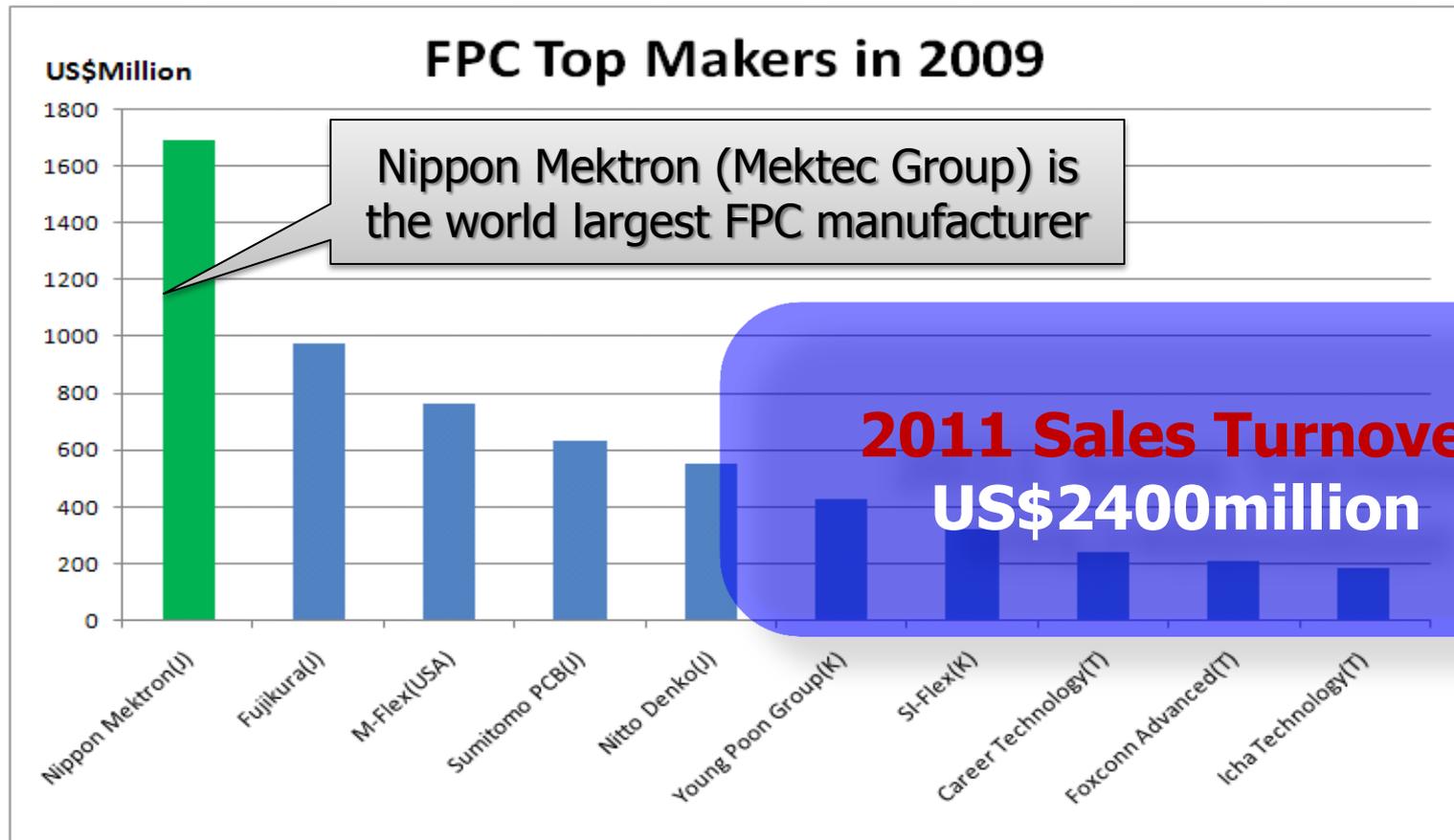


# Outline

- [Short Company Profile of Nippon Mektron](#)
- [Developments of Printed FPCs](#)
  - ❑ PE resist for long FPCs
  - ❑ Flexible Touch Sensor Panel(TSP) application
  - ❑ Single-sided Printed FPCs
  - ❑ Double-sided Printed FPCs
  - ❑ Smart Printed FPCs
- [Summary](#)



# Sales Turnover of Global FPC Top makers



# Global Production Network

*13 Factories in 6 Countries*



**Main Factories**



Minami-Ibaraki Plant (Japan)



Kashima Plant (Japan)



Ushiku Okubara Plant (Japan)



Kaohsiung Plant (Taiwan)



Tainan Plant (Taiwan)



Ayutthaya Plant (Thailand)



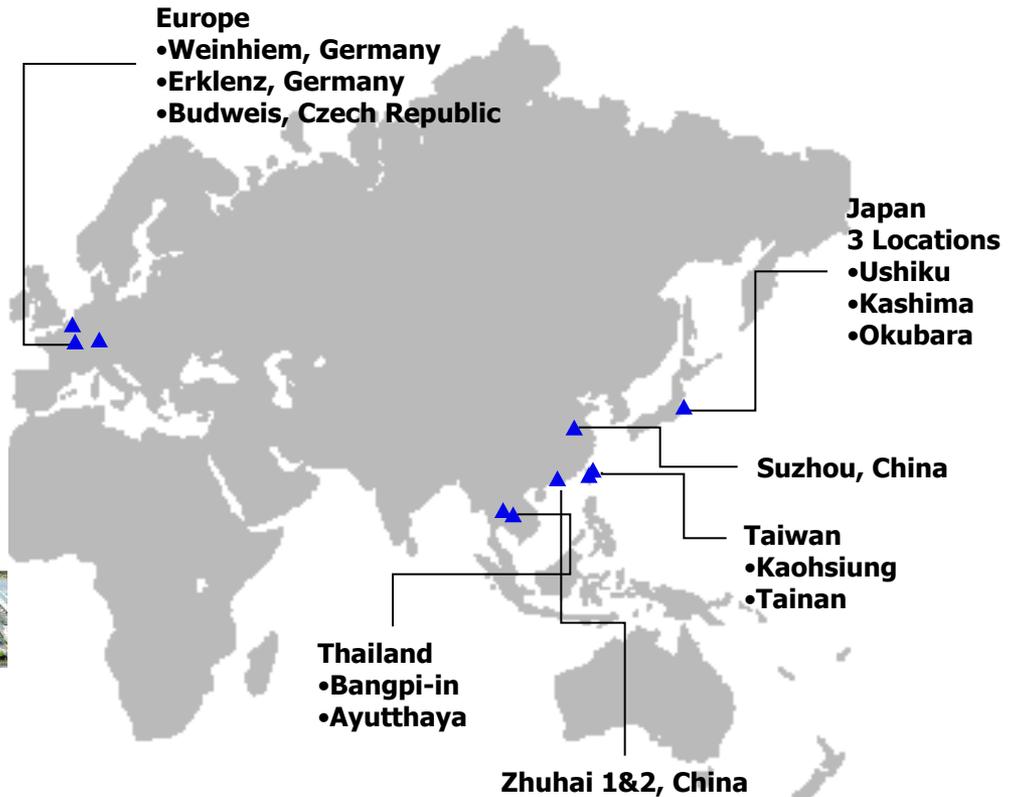
Zhuhai Plant (China)



Longshan Plant (China)



Suzhou Plant (China)

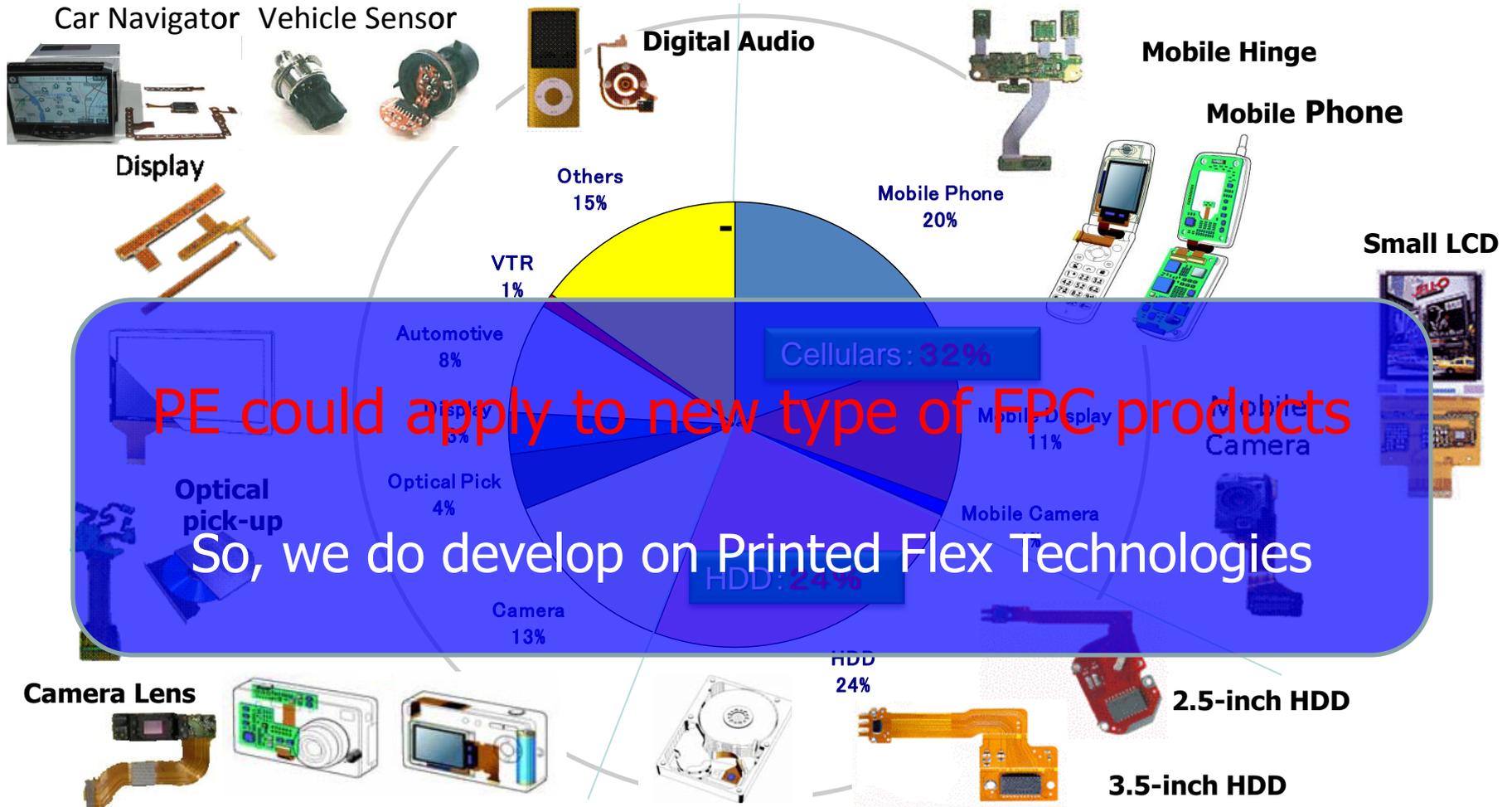


# Global Sales Support

*25 Sales Locations in 10 Countries*



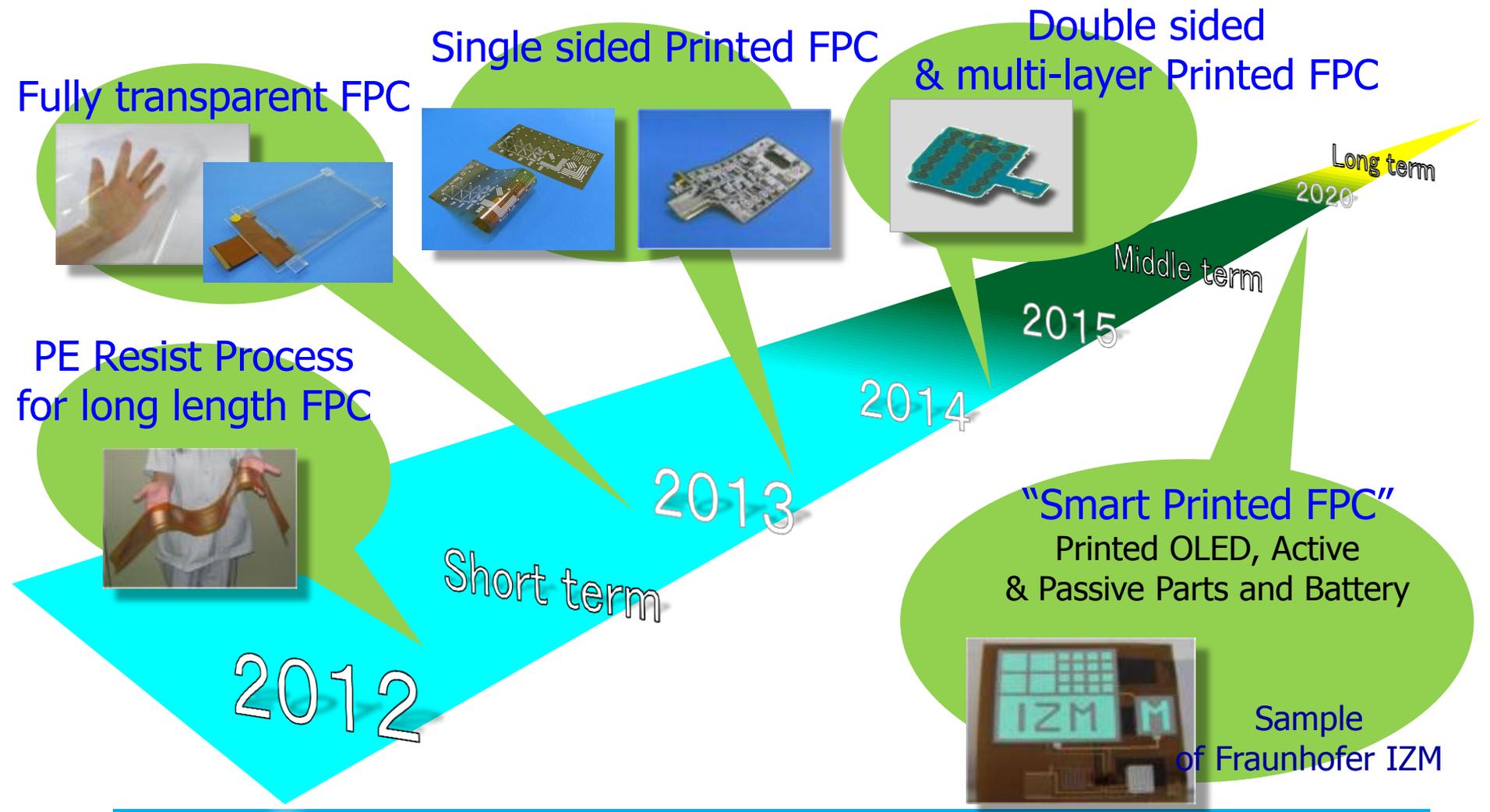
# FPC Sales Mix of Mekttec Group



PE could apply to new type of FPC products

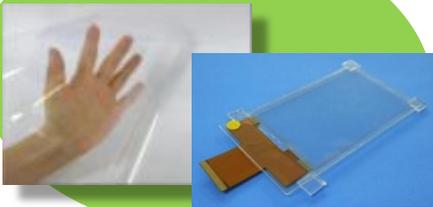
So, we do develop on Printed Flex Technologies

# Nippon Mektron Printed Flex Technology Roadmap

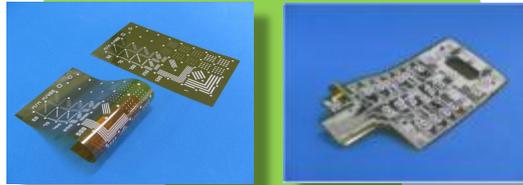


# Nippon Mektron Printed Flex Technology Roadmap

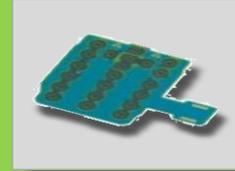
Fully transparent FPC



Single sided Printed FPC



Double sided & multi-layer Printed FPC



Long term  
2020

Middle term

2015

2014

2013

Short term

2012

PE Resist Process  
for long length FPC



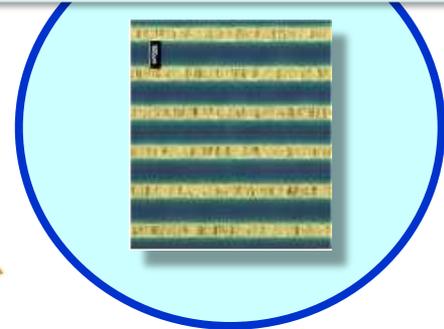
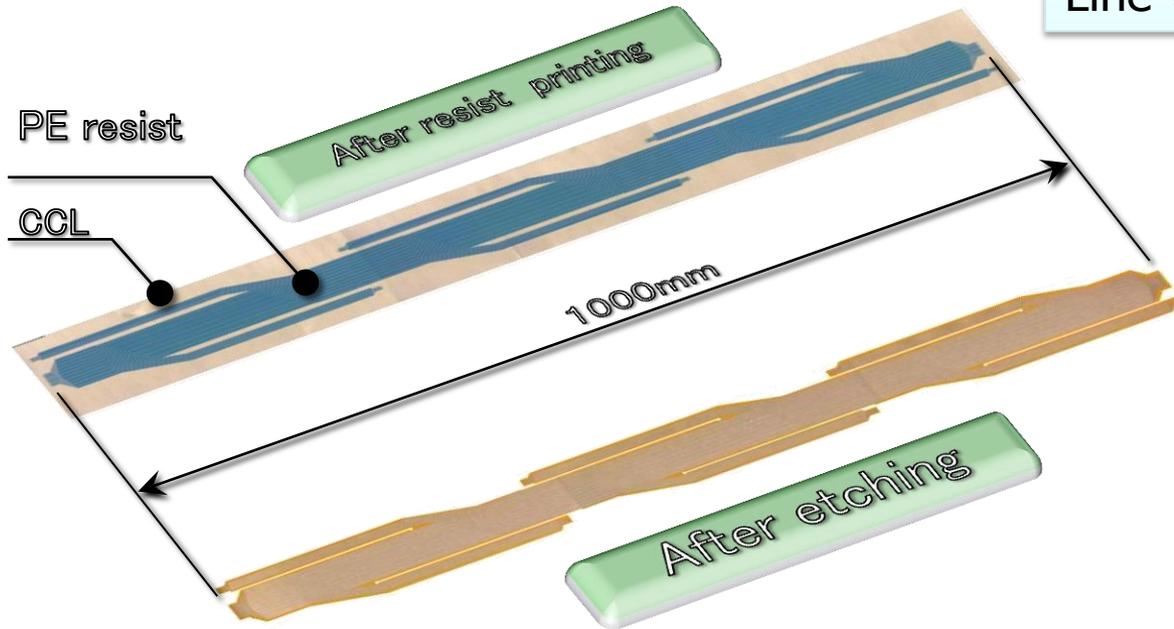
"Smart Printed FPC"  
Printed OLED, Active  
& Passive Parts and Battery



Sample  
of Fraunhofer  
IZM

# PE Resist Process for long length FPC

Line Width/Space < 100/100 $\mu$ m



No need to have:  
-Dry film lamination  
-DF Exposure  
-DF development

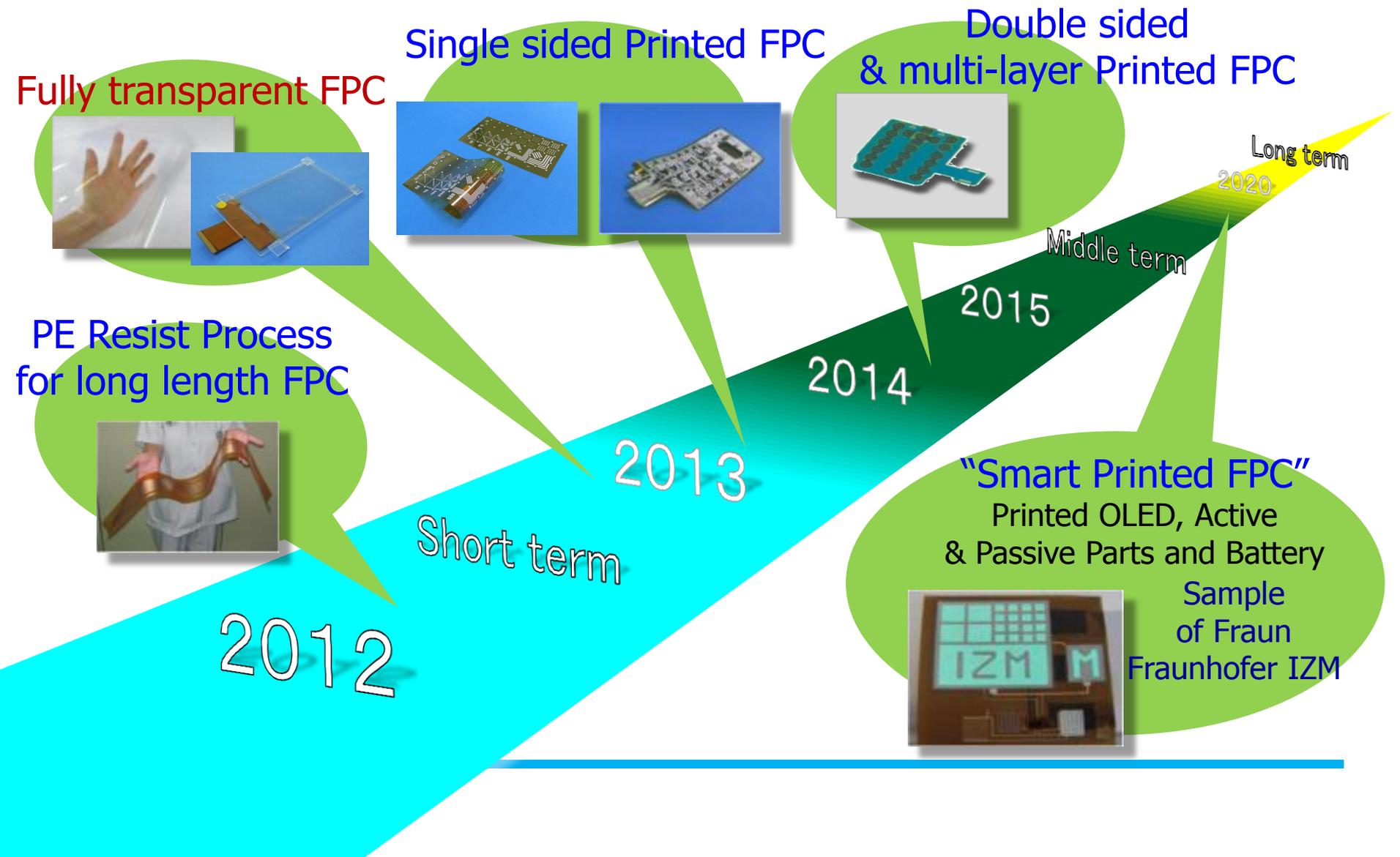


+

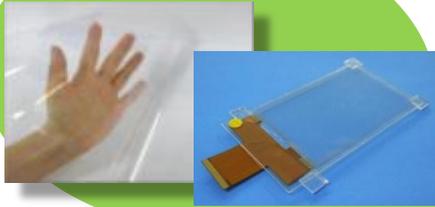


-Low Cost  
-Less energy & Material

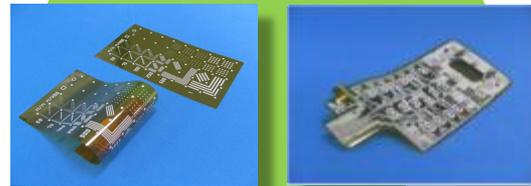
# Nippon Mektron Printed Flex Technology Roadmap



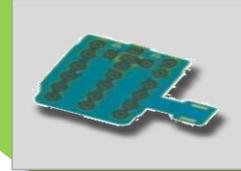
Fully transparent FPC



Single sided Printed FPC



Double sided & multi-layer Printed FPC



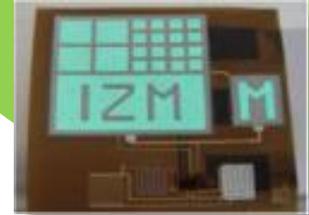
PE Resist Process for long length FPC



"Smart Printed FPC"

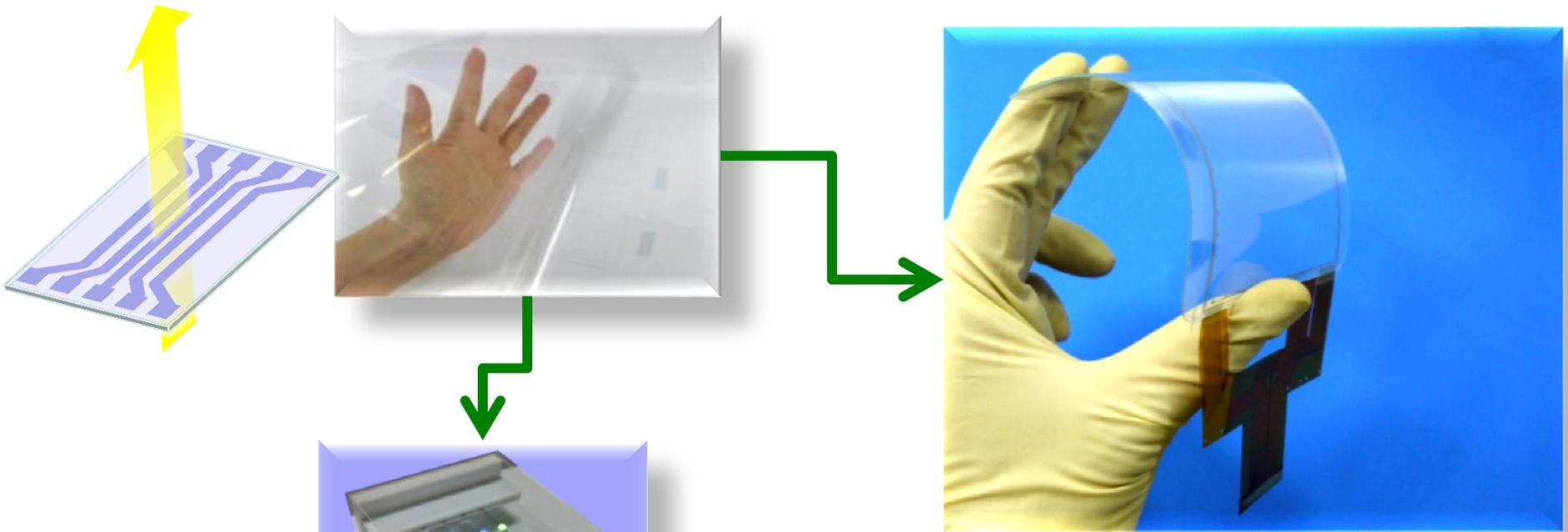
Printed OLED, Active & Passive Parts and Battery

Sample of Fraunhofer IZM



## Flexible Touch Sensor Panel(TSP) Development

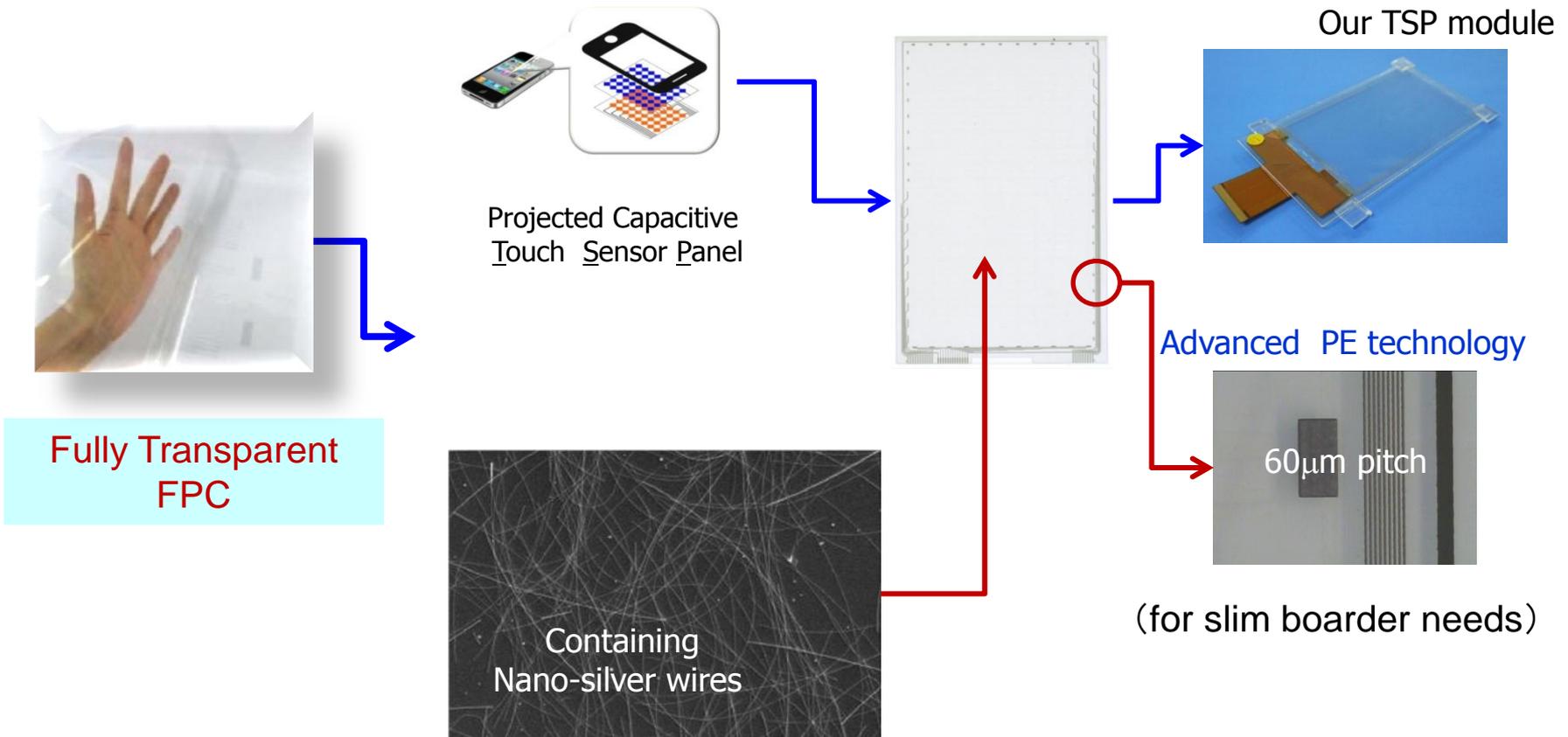
Fully Printed Transparent FPC



LED Transparent FPC

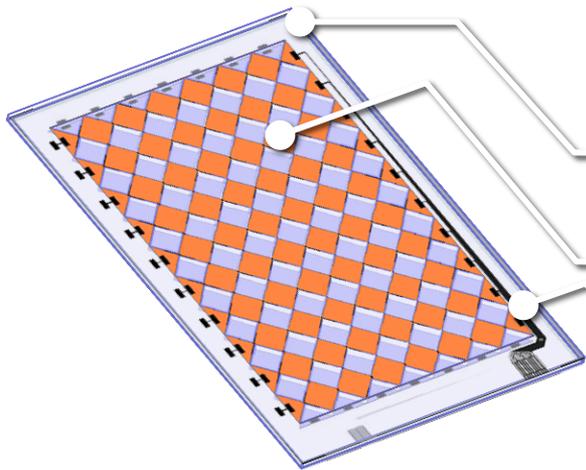
Flexible Printed TSP Module

# Touch Sensor Panel Application of Fully Transparent Flex



# Touch Sensor Panel Application of Fully Transparent Flex

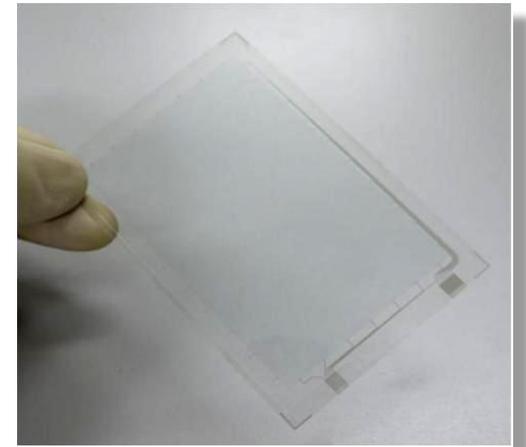
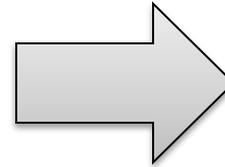
To realize "Projected Capacitive Type"



◇ PET

◇ AgNW

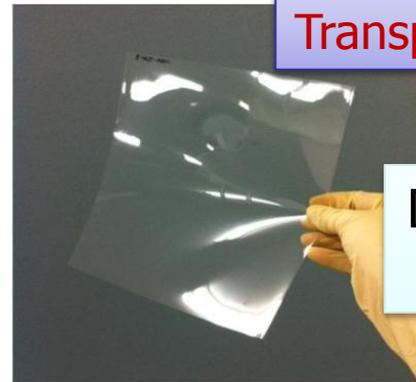
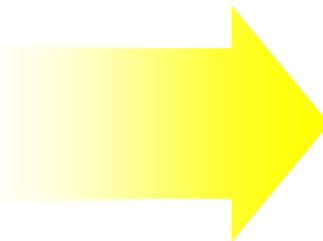
◇ nano-Silver  
Paste



Sheet resistivity <math>< 80 \Omega / \square</math>  
Transparent rate > 90%

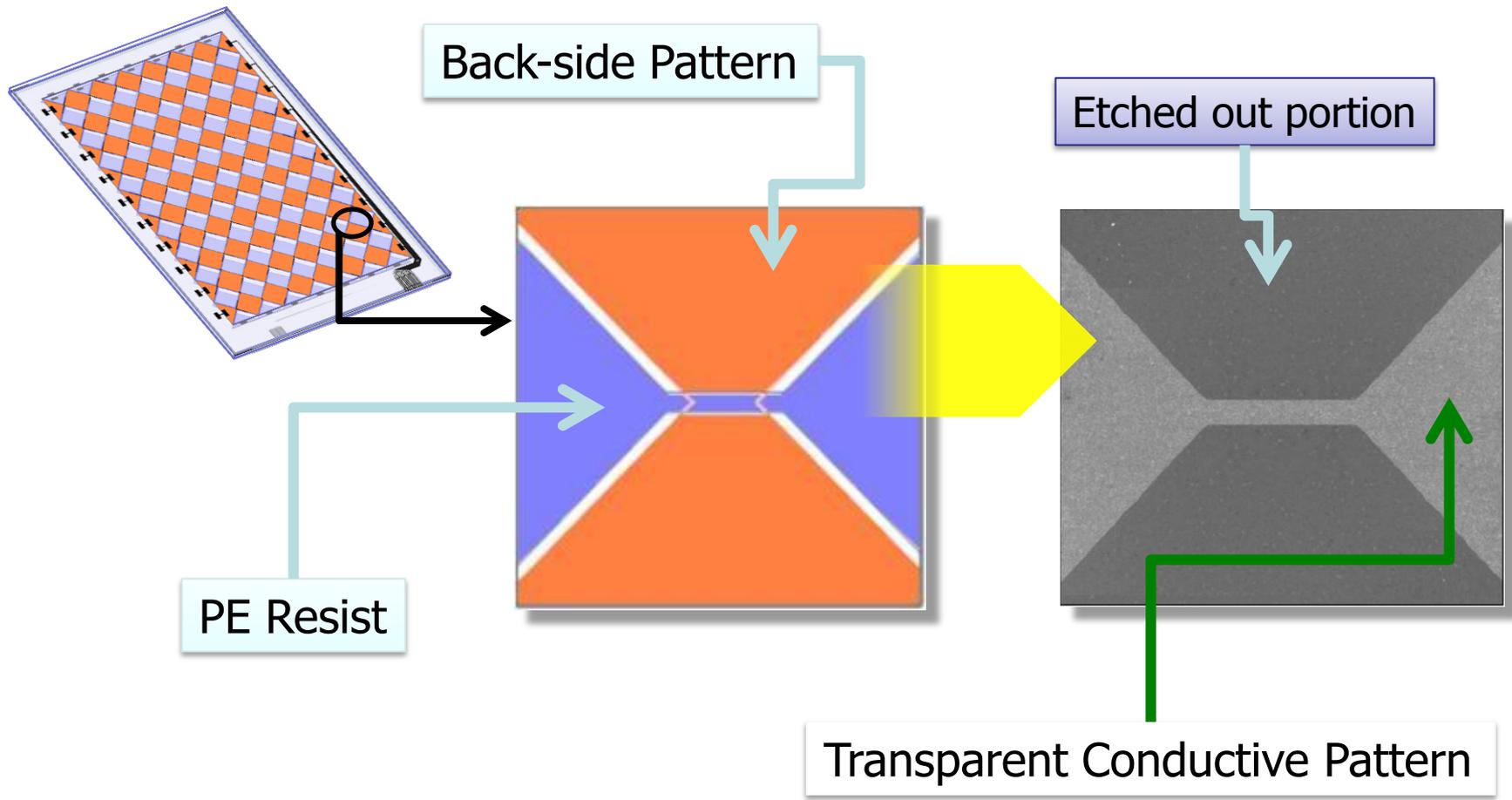


Paste containing  
Nano-silver wires

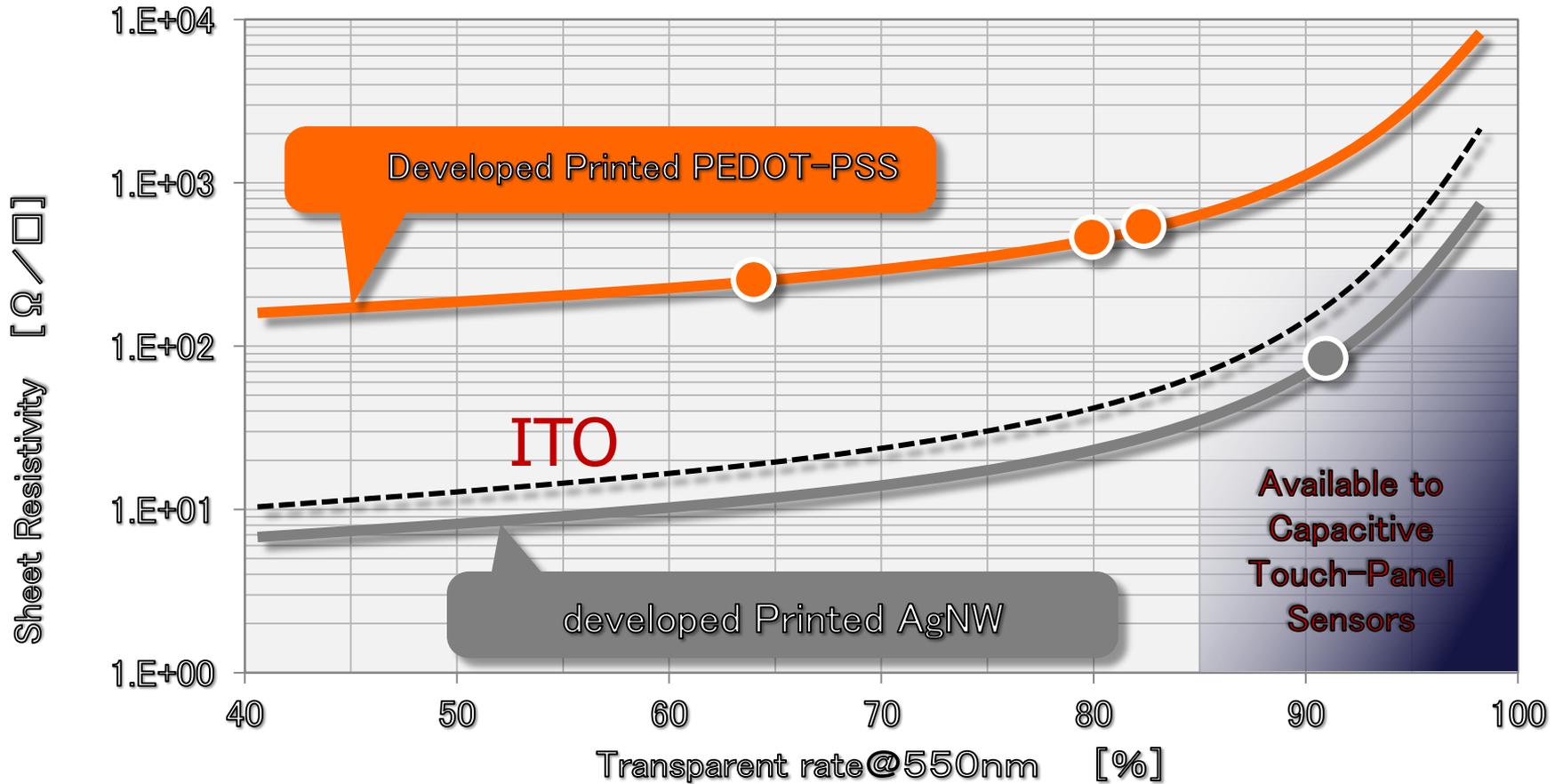


Double-side Printing  
AgNW onto PET

# AgNW formation by PE

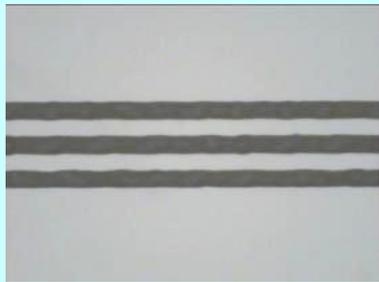


# Sheet Resistivity vs. Transparent Rate

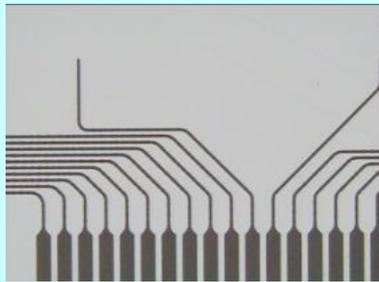


# Ag printed wirings

Conventional Ag Printing

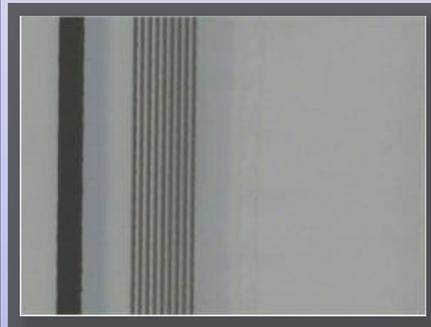


$L/S=100/100\mu\text{m}$

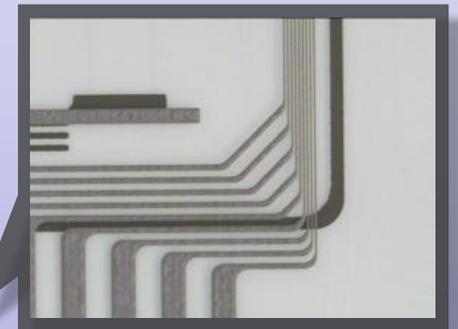
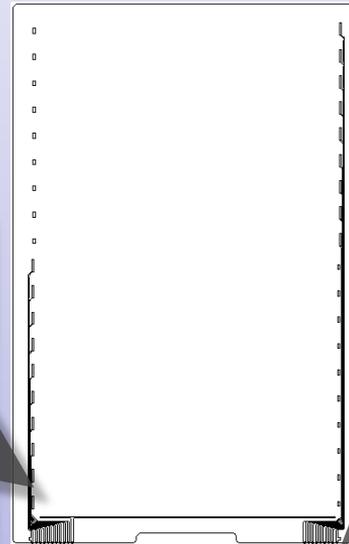


Pitch=500 $\mu\text{m}$

Developed "Super Fine Ag Printing"

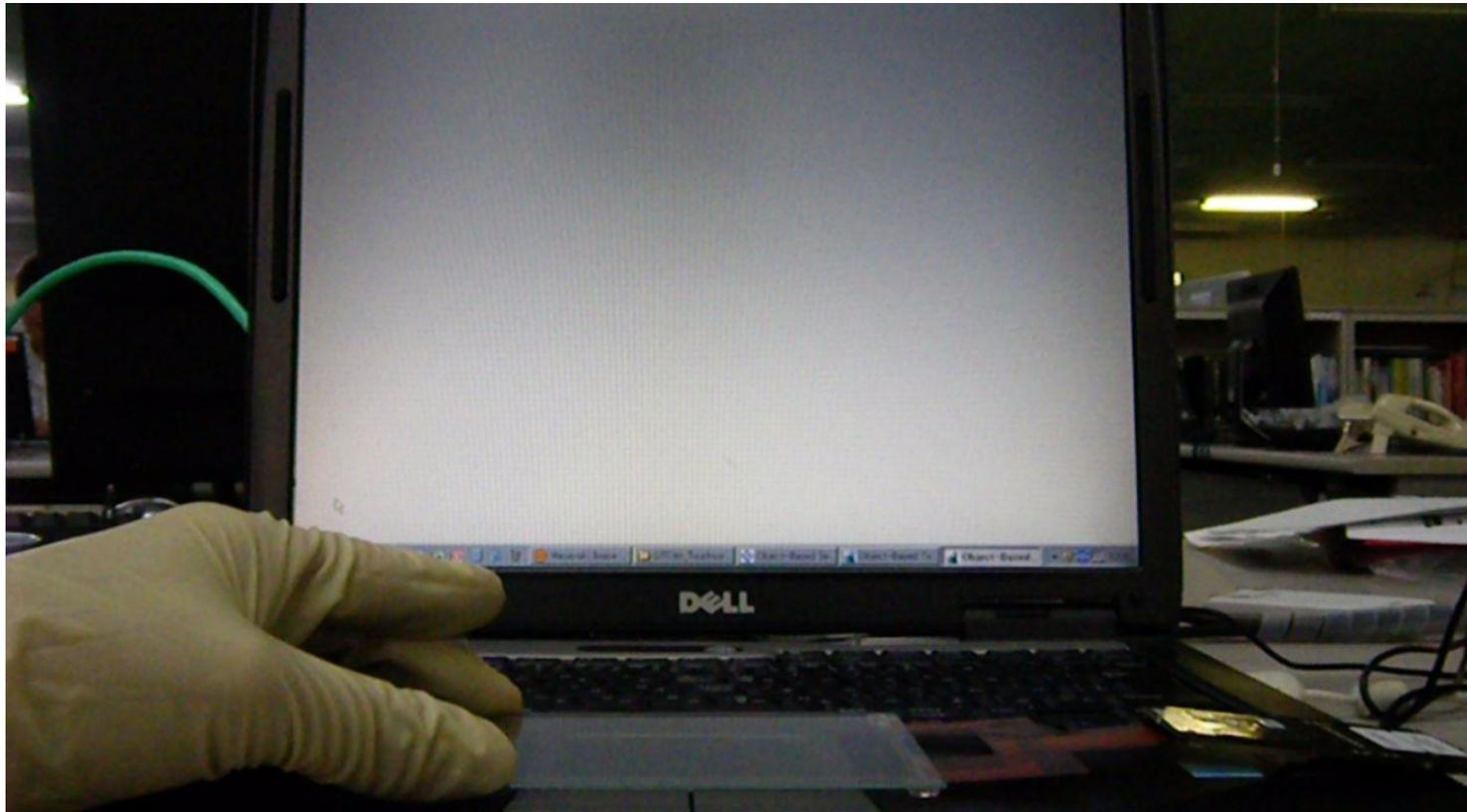


$L/S=30/30\mu\text{m}$



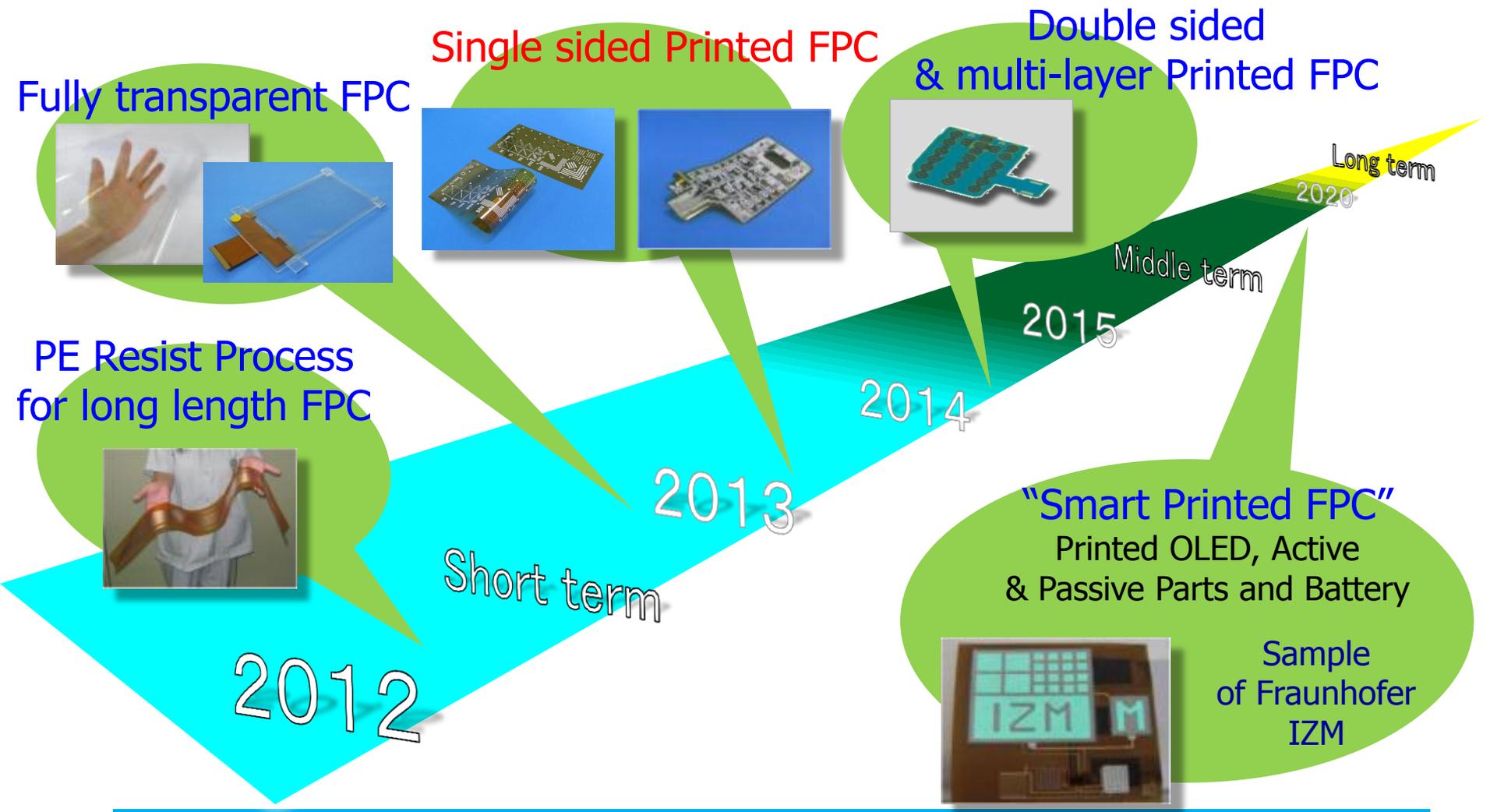
$L/S=30/30\mu\text{m}$

## Projected Capacitive Touch Sensor Panel



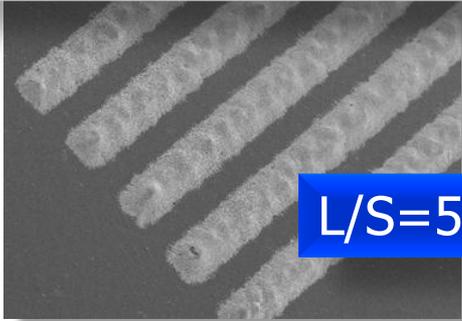
Video demonstration of developed TSP module

# Nippon Mektron Printed Flex Technology Roadmap

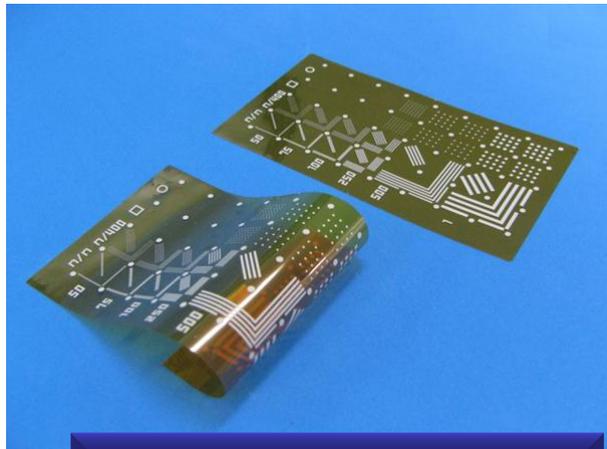


# Single-sided Printed FPCs

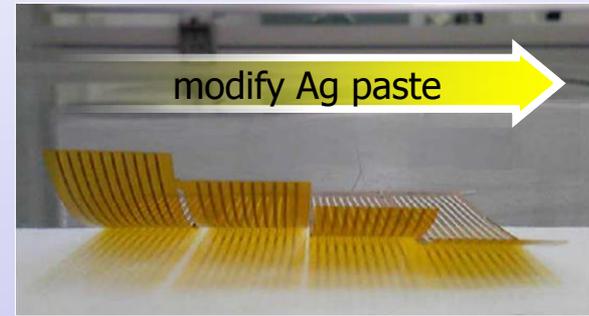
Newly developed Ag paste



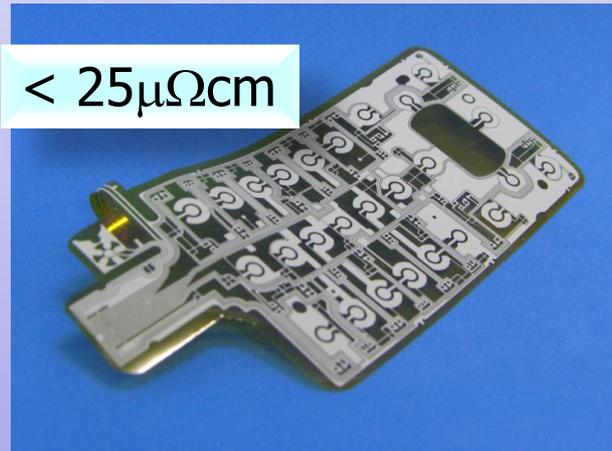
$L/S=50/50\mu\text{m}$



R2R print processing

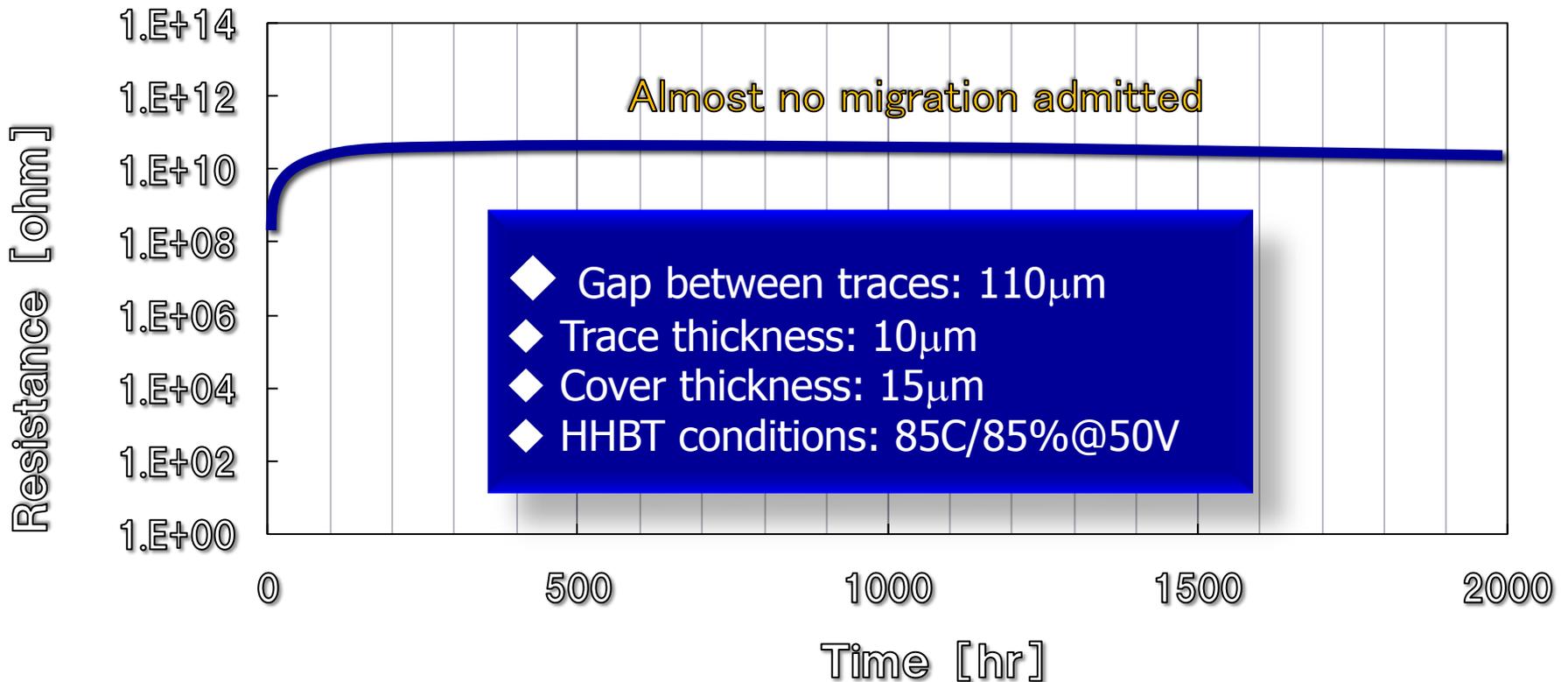


$< 25\mu\Omega\text{cm}$



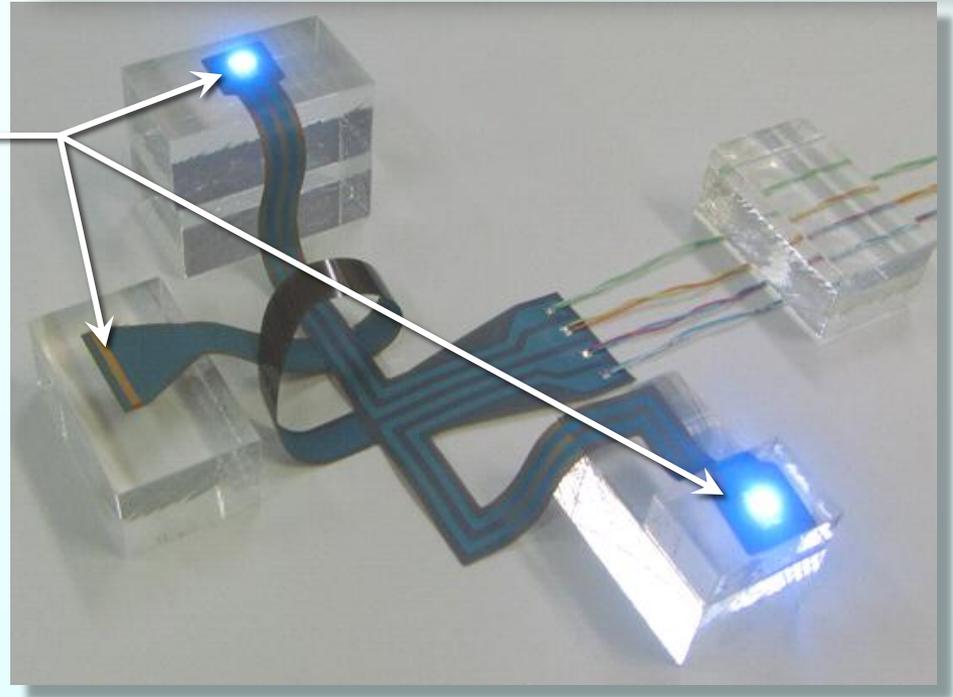
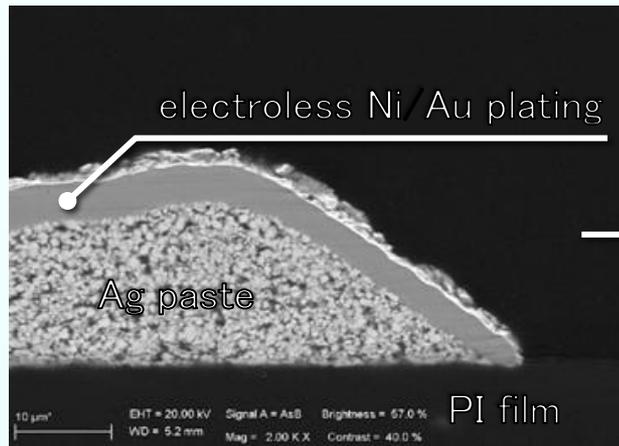
# Single-sided Printed FPCs

Less or no migration is key issue!!

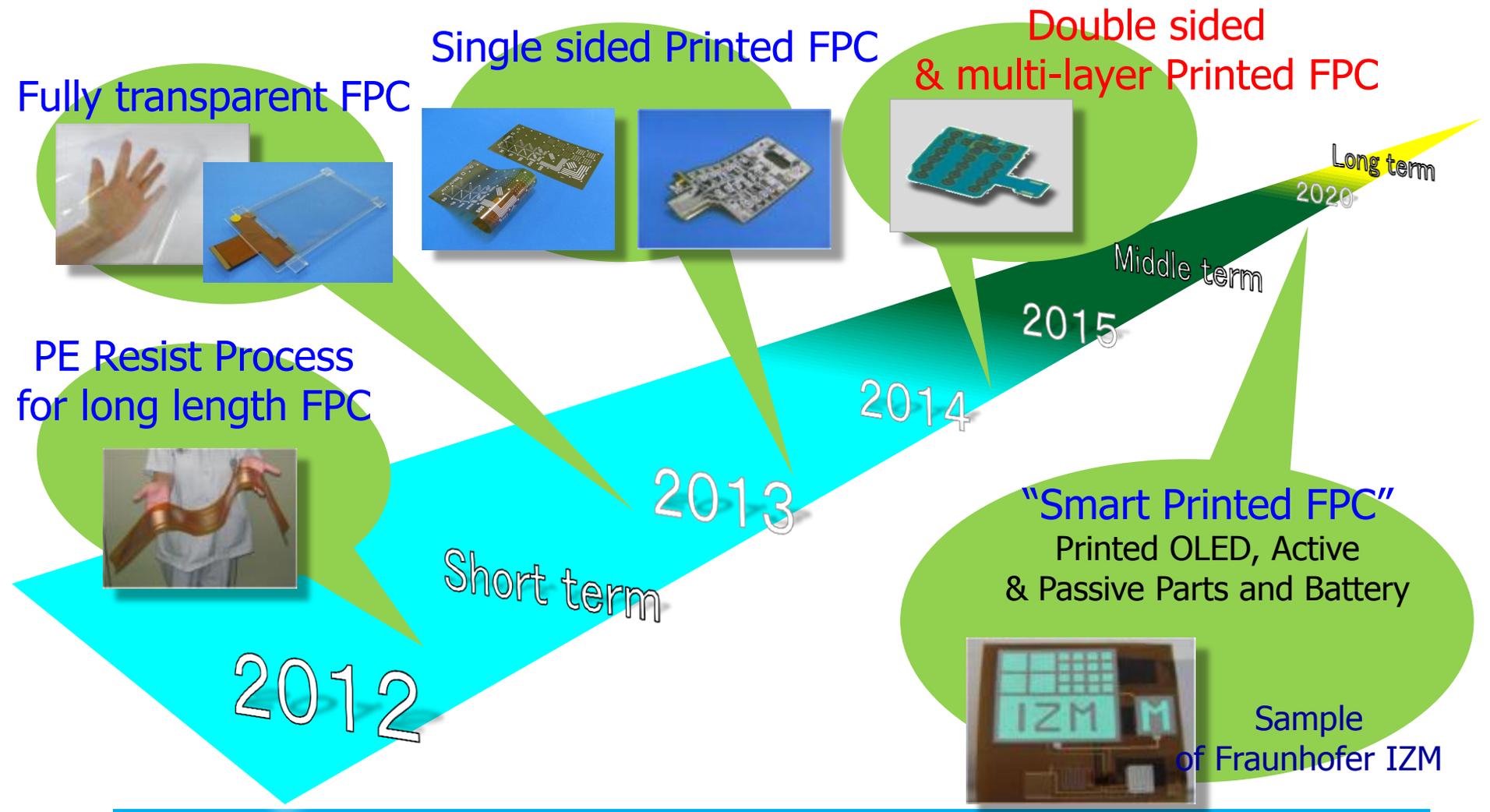


# Single-sided Printed FPCs

## LED assembled SS Printed FPCs

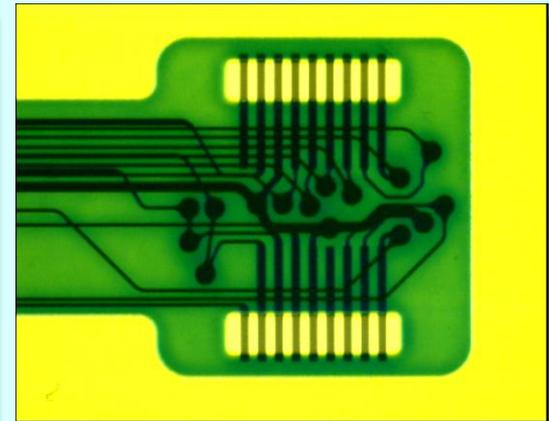
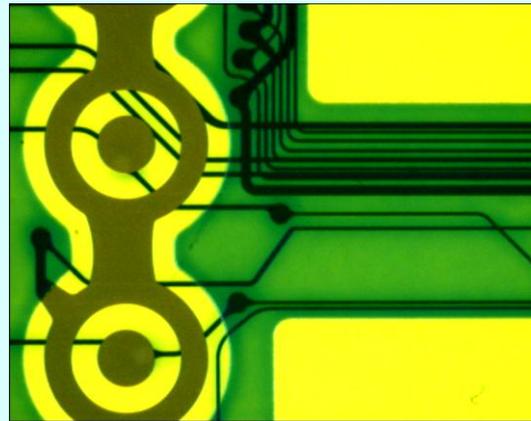
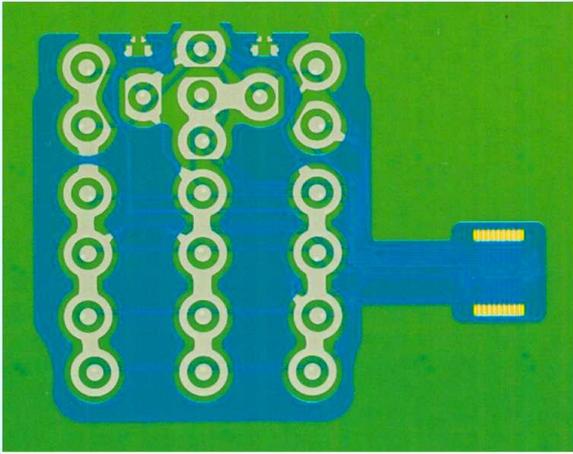


# Nippon Mektron Printed Flex Technology Roadmap



# Double-sided Printed FPC

Top view of the sample



Second Ag layer

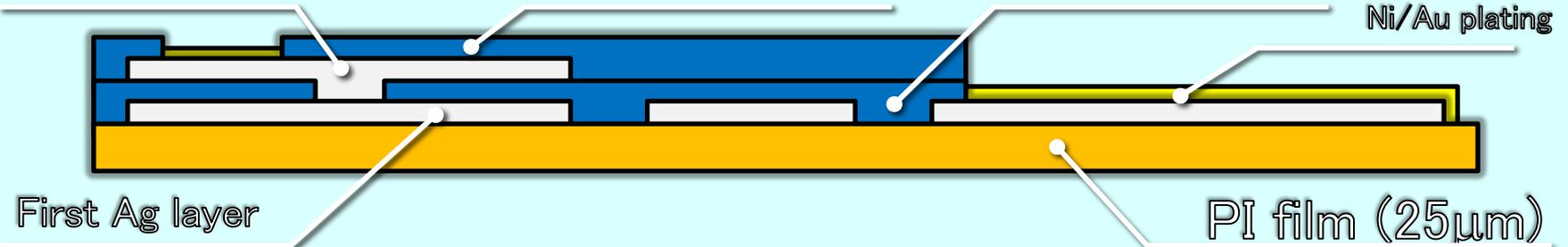
Printed cover

Printed Inter-layer

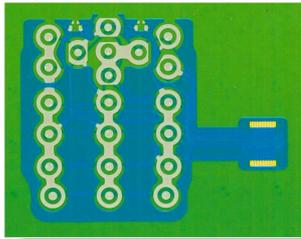
Ni/Au plating

First Ag layer

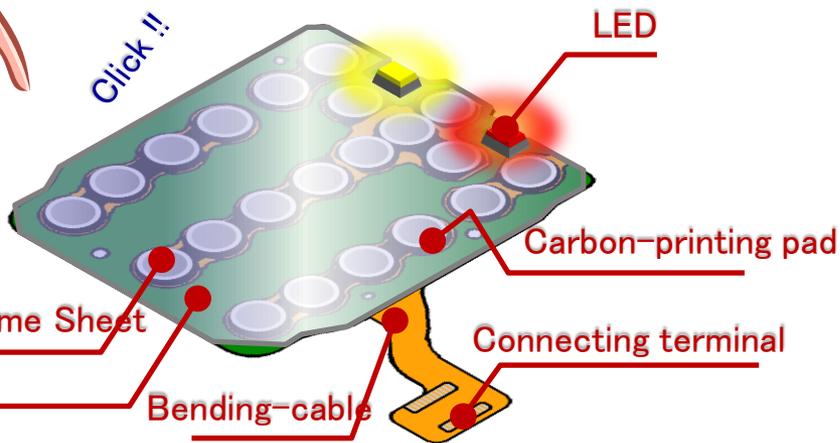
PI film (25 $\mu$ m)



# Double-sided Printed FPC



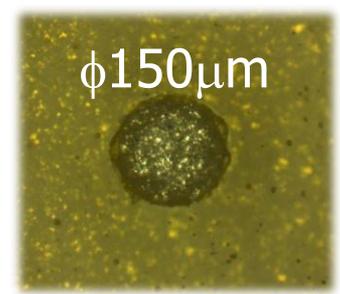
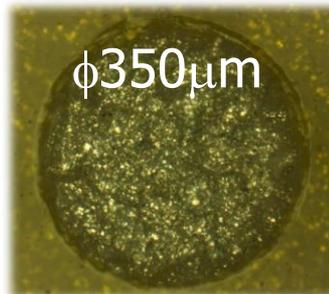
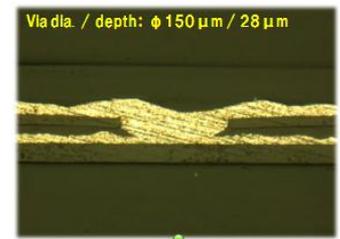
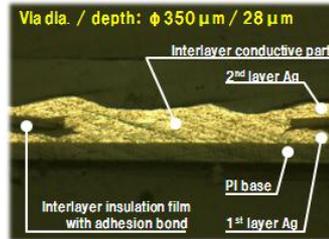
Click !!



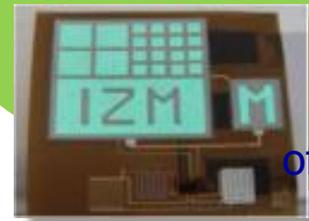
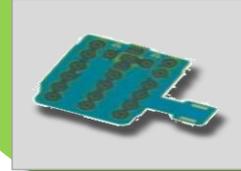
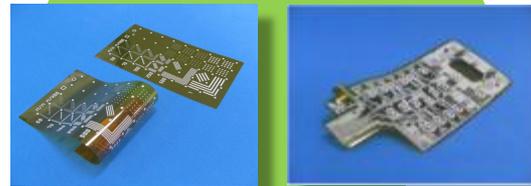
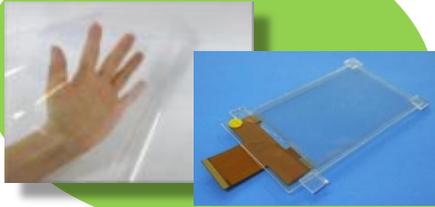
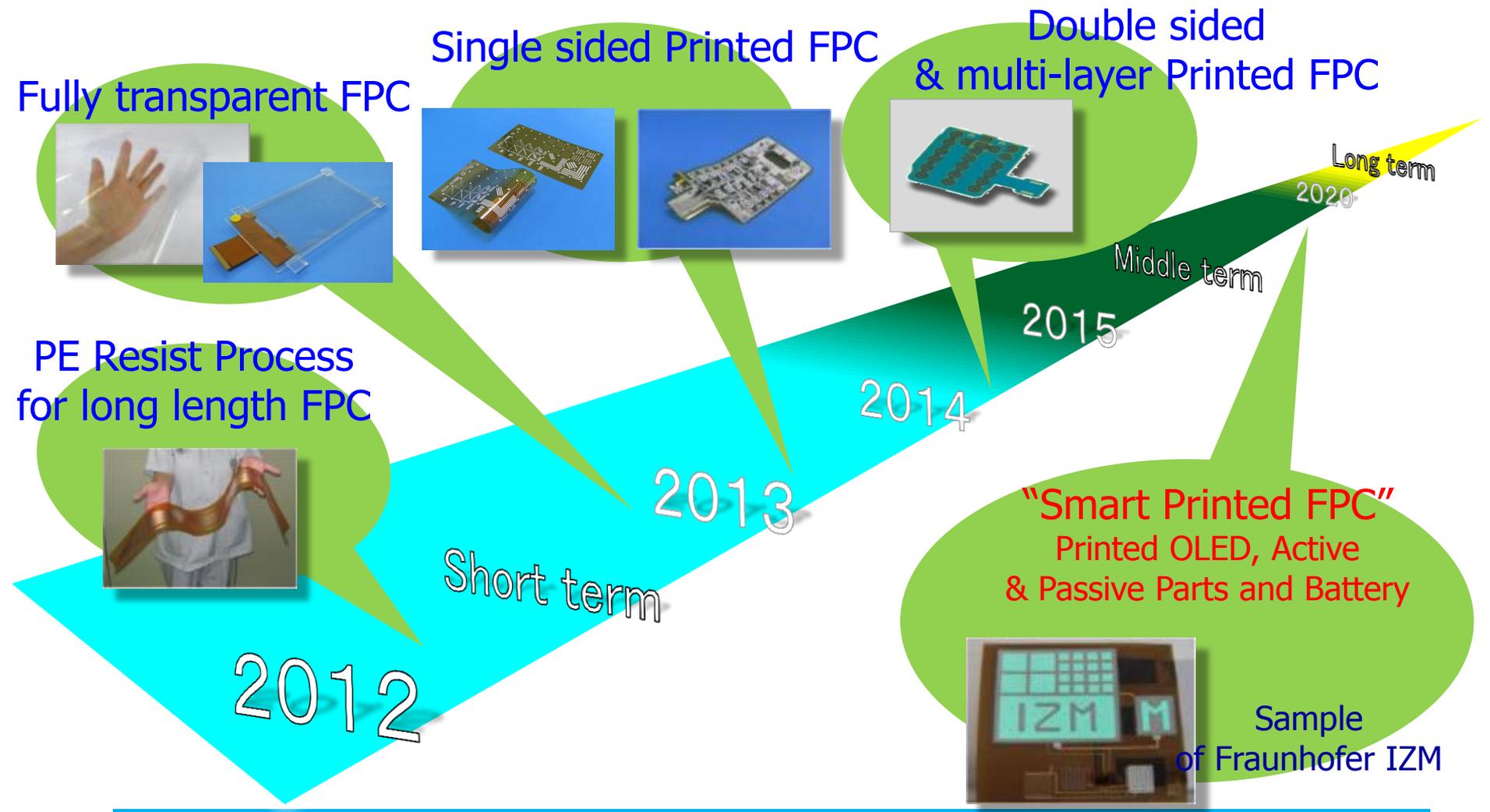
Vias



## Via formation

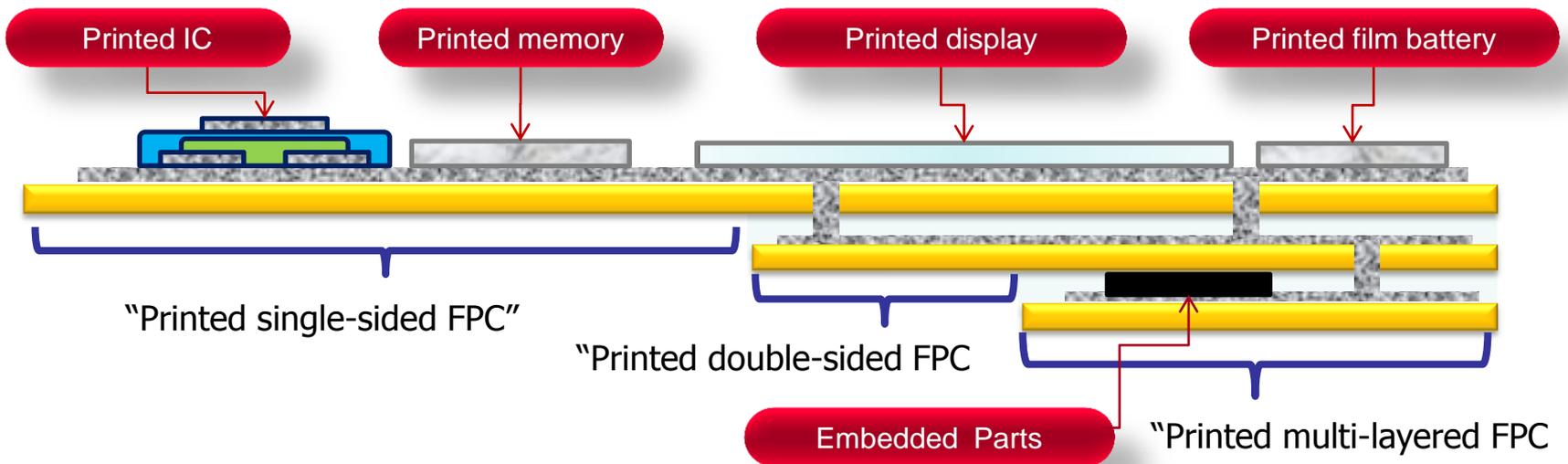


# Nippon Mektron Printed Flex Technology Roadmap



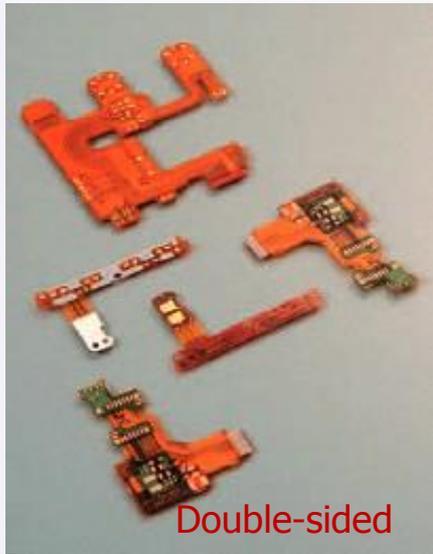
# Smart Printed FPCs

## Schematic of "Smart Printed FPCs"

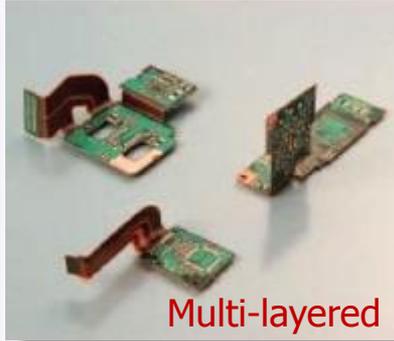


# Summary

## Current FPC Products



Double-sided



Multi-layered



Single-sided

Photo-lithography products  
-Subtractive etching/additive plating-

## New FPC Products by “Printed Electronics”



# The end

## Thank you for your attention

=====

Dr. Hirofumi Matsumoto/Operating Officer, Division Manager  
Nippon Mektron, Ltd. Product Development Planning Office  
757 Amaboki, Tsukuba-shi, Ibaraki-ken 〒300-1253  
e-mail: [hiromatu@mektec.mektron.co.jp](mailto:hiromatu@mektec.mektron.co.jp) URL <http://www.mektron.co.jp/>

=====

